HIGH DENSITY INTEGRATED CIRCUIT PACKAGE

ABSTRACT OF THE DISCLOSURE

A high density integrated circuit package (30) including a substrate (70) having an opening (86) and first and second surfaces (92, 94), a plurality of routing strips (82) being integral with the substrate (70) and extending into the opening (86), a plurality of pads (100) disposed on the first and second surfaces (92, 94) and electrically connected with at least one of the routing strips (82), vias (84) electrically connecting the pads (100, 108) disposed on the first surface (92) with the pads (100) disposed on the second surface (94), a chip (50) adhered to the substrate (70) having bonding pads (120), wire bonding (80) electrically connecting at least one bonding pad (120) to at least one of the routing strips (82) and potting material (90) filling the opening (86) is disclosed.

Figure 1